				_						September	
PCN Number:		20230918002.1						PCN Date:	18, 2023		
Title:	Title: Qualification of CDAT as an alternate Assembly site for select devices										
Custome	Customer Contact: Change Management Team Dept: Quality Services										
Proposed 1 st Ship Date: Dec				Dec 17, 2023				mple reques			
*Sample	ereques	ts rece	ived a	after Oct 18,	2023	will i	not be s	uppo	rted.		
Change											
	embly Site			Design					Wafer Bump Material		
	embly Pro				Data Sheet			H	Wafer Bump Process		
	embly Mat		Atau.		Part number change			H	Wafer Fab Site		
	hanical S king/Shipp	•			Test Site			H	Wafer Fab Material Wafer Fab Process		
Раск	Kiriy/Siripj	Jiriy/ Lat	Jeiling		PCN Details				Waler Fab Process		
Descript	tion of Cl	hanger		P	CIVE	Ctall	<u> </u>				
Descript		.anger									
				d is announci s listed below	v. Co						
				JCE	TC8		PI	HI	CDAT		
	Mold (Compou	nd	SID#1310	10100	455	4222	2198	422219	8	
Reason	for Chan	ge:									
Supply c	ontinuity										
Anticipa	ted impa	act on I	Form,	Fit, Functio	n, Qu	ality	or Relia	bility	(positive / ı	negative):	
None	None										
Impact	on Enviro	onmen	tal Ra	tings							
				tus of enviro							
	RoHS			REACH			reen St			C 62474	
⊠ No C	Change		⊠ No	Change		⊠N	o Chang	е	⊠ No C	Change	
			. 161								
Changes	s to prod			ation resulti							
Assemb	oly Site	Ass		Site Origin 2L)	As	sembl	y Countr (23L)	y Cod	e As:	sembly City	
		J	IC8		CHN				Suqian		
PHI			PHI		PHL				В	aguio City	
CD	AT		C	DA			CHN			Chengdu	
Sample p	roduct sl	hippina	label	(not actual)	produc	ct labe	 el)				

TEXAS INSTRUMENTS MADE IN: Malaysia 2DC: 2Q:

(1P) SN74LS07NSR (a) 2000 (D) 0336 (31T)LOT: 3959047MLA (4W) TKY(1T) 7523483S12

(P) (2P) REV:

(2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO:USA (22L) ASO: MLA (23L) ACO: MYS

OPT: ITEM: 5A (L)T0:1750

MSL 2 /260C/1 YEAR SEAL DT MSL 1 /235C/UNLIM 03/29/04

Product Affected:

_				
	SN562202DRLR	TLV62568APDRLR	TLV62569APDRLR	TPS562202SDRLR
	SN562207DRLR	TLV62568APDRLT	TLV62569APDRLT	TPS562207DRLR
	SN562231DRLR	TLV62568DRLR	TLV62569DRLR	TPS562207SDRLR
	SN562231DRLT	TLV62568DRLT	TLV62569DRLT	TPS563207DRLR
	SN563207DRLR	TLV62568PDRLR	TLV62569PDRLR	TPS563207SDRLR
	SN563232DRLR	TLV62568PDRLT	TLV62569PDRLT	TPS563231DRLR
	TLV62568ADRLR	TLV62569ADRLR	TPS562202DRLR	TPS563231DRLT
	TLV62568ADRLT	TLV62569ADRLT		



TI Information Selective Disclosure

Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: TPS562231DRLR
ED	Electrical Characterization, side by side	(per datasheet)	Pass
FLAM	Flammability (UL-1694)	-	3/15/0
HAST	Biased HAST, 130C/85%RH	96 Hours	3/231/0
HTOL	Life Test, 125C	1000 Hours	3/231/0
HTSL	High Temp Storage Bake 170C	420 Hours	3/231/0
LFA	Lead Finish Adhesion	Leads	3/45/0
LI	Lead Fatigue	Leads	3/54/0
LI	Lead Pull	Leads	3/72/0
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	Pass
PD	Physical Dimensions	(per mechanical drawing)	3/15/0
SA	Salt Atmosphere	24 Hrs	3/66/0
SD	Solderability	Pb Free	3/66/0
TC	Temperature Cycle, -65/150C	500 Cycles	3/231/0
UHAST	Unbiased HAST 130C/85%RH	96 Hours	3/231/0
VM	Visual / Mechanical	-	3/984/0

⁻ Qual Device TPS562231DRLR is qualified at LEVEL1-260CG

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/ Green/Pb-free Status:

Qualified Pb-Free (SMT) and Green

TI Qualification ID: 20200213-132963

Change Number: C2004305

For questions regarding this notice, e-mails can be sent to Change Management team or your local Field Sales Representative.

⁻ Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7 eV 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

⁻ The following are equivalent HTSL options based on an activation energy of 0.7eV 150C/1k Hours, and 170C/420 Hours - The following are equivalent Temp Cycle options per JESD47 -55C/125C/700 Cycles and -65C/150C/500 Cycles

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